



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

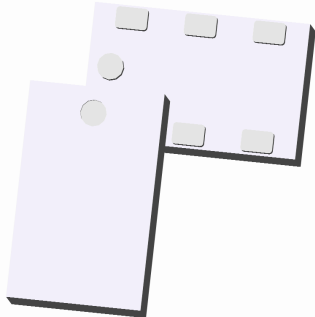
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Xinger®



Ultra Low Profile 0805 3 dB, 90° Hybrid Coupler

Description

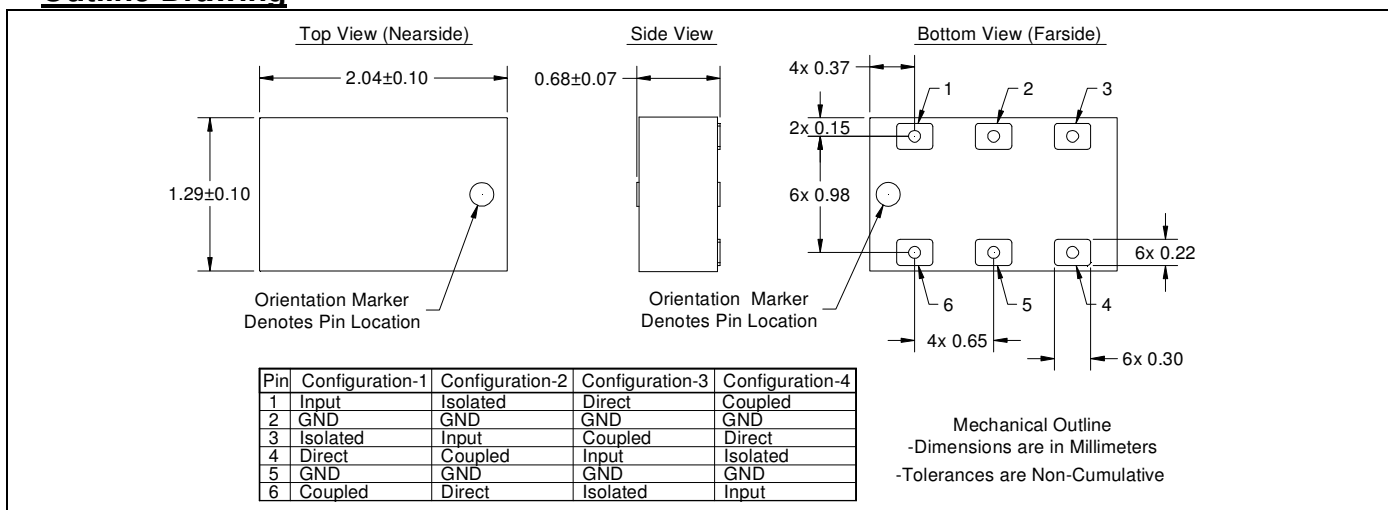
The C3337J5003AHF is a low cost, low profile sub-miniature high performance 3 dB coupler in an easy to use surface mount package. It is designed for LTE, WiMax and WiBro applications. The C3337J5003AHF is ideal for balanced power and low noise amplifiers, plus signal distribution and other applications where low insertion loss and tight amplitude and phase balance are required. The C3337J5003AHF is available on tape and reel for pick and place high volume manufacturing.

All of the Xinger components are constructed from ceramic filled PTFE composites which possess excellent electrical and mechanical stability. All parts have been subjected to rigorous qualification testing and units are 100% RF tested.

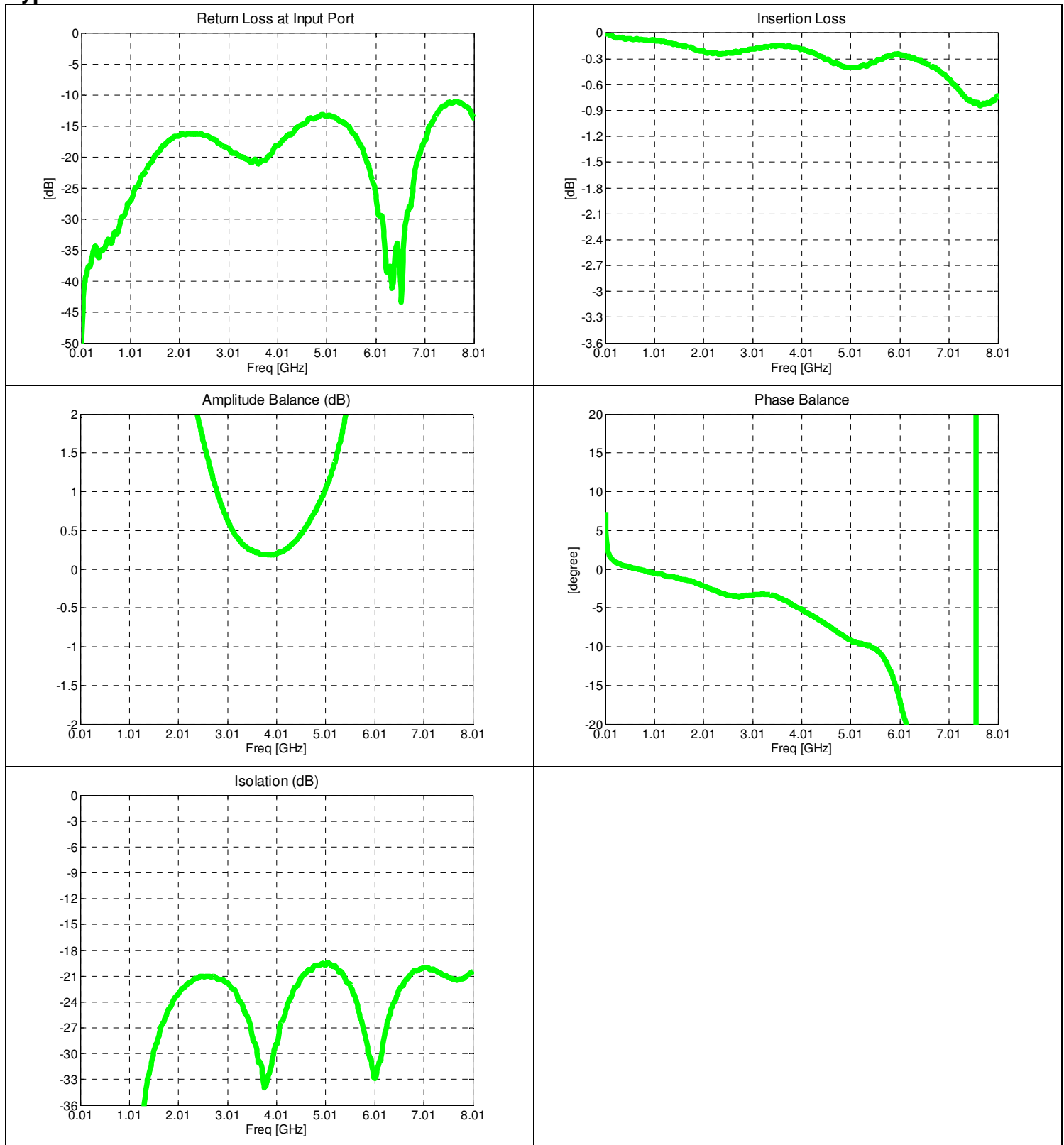
Detailed Electrical Specifications: Specifications subject to change without notice.

Features:	Parameter	ROOM (25 °C)						Unit
		Min.	Typ.	Max	Min.	Typ.	Max	
• 3070 – 3805 MHz	Frequency	3300		3700	3070		3805	MHz
• 0.7mm Height Profile	Port Impedance		50			50		Ω
• High Isolation, Low Loss	Return Loss	15	18		15	18		dB
• LTE Bands: 22, 42, 43	Isolation	18	22		18	22		dB
• WiMax WiBro Applications	Insertion Loss		0.2	0.3		0.2	0.4	dB
• Surface Mountable	Amplitude Balance		0.3	1		0.3	1.2	dB
• Tape & Reel	Phase Balance (relative to 90°)		3	7		4	7	Degrees
• Non-conductive Surface	Group Delay	0.05	0.055	0.06	0.05	0.06	0.07	ns
• RoHS Compliant	Power Handling (85°C)			4			4	Watts
• Halogen-Free	Power Handling (105 °C)			3			3	Watts
• 100% RF Tested	Operating Temperature	-55		105	-55		105	°C
• -55 °C to 105 °C								

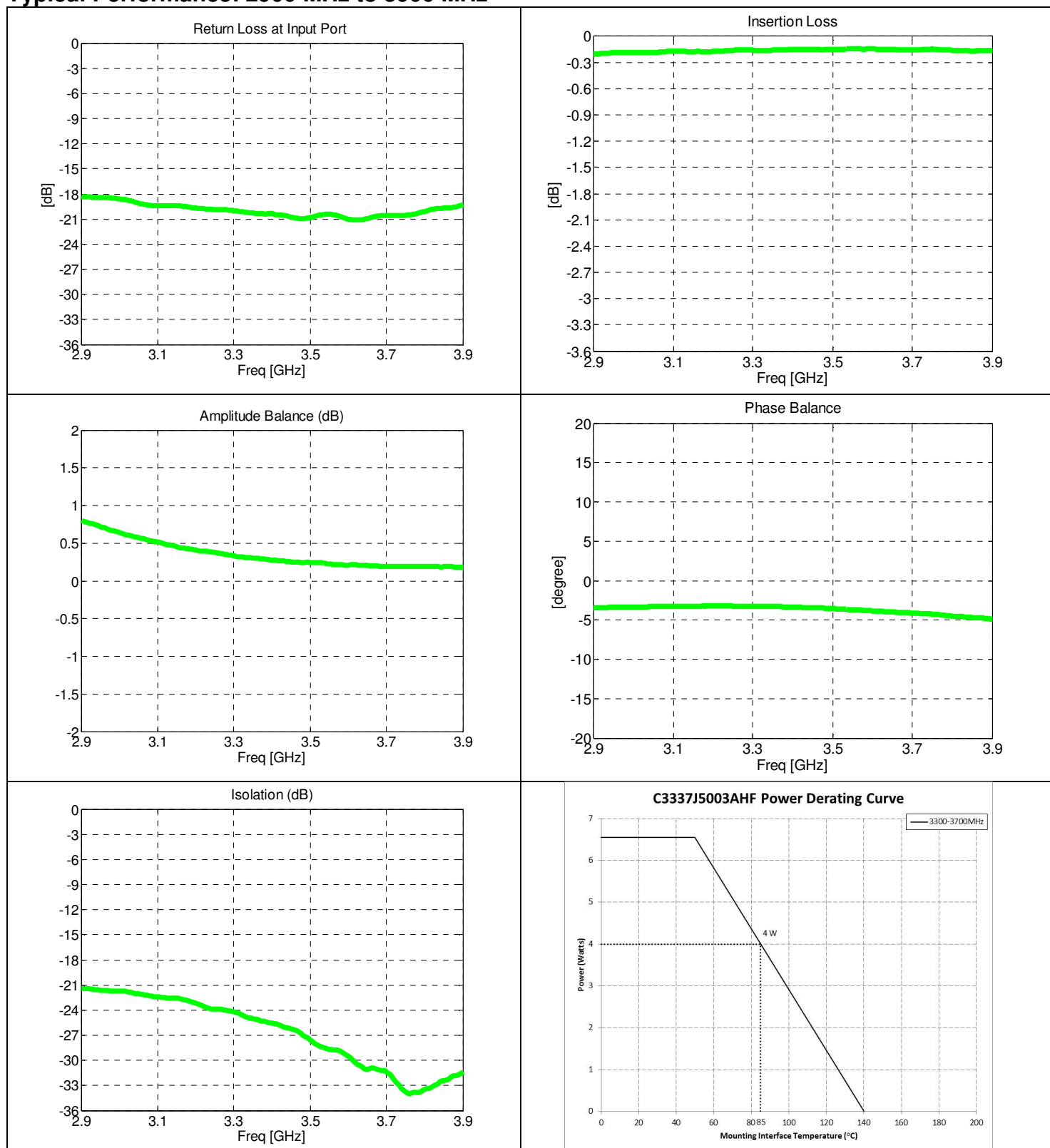
Outline Drawing



Typical Broadband Performance: 10 MHz to 8010 MHz



Typical Performance: 2900 MHz to 3900 MHz



Definition of Measured Specifications

Parameter	Definition	Mathematical Representation <i>i, j, k, m</i> is denoted as the port index of input, isolated, direct and coupled port for specific pin configuration shown in the table
Return Loss	The impedance match of the coupler to a 50Ω system. Return Loss is an alternate means to express VSWR.	$20\log_{10}(S_{ii})$
Isolation	The input power divided by the sum of the power at the two output ports.	$20\log_{10} S_{ji} $
Insertion Loss	The input power divided by the sum of the power at the two output ports.	$10\log_{10}(S_{mi} ^2 + S_{ki} ^2)$
Amplitude Balance	The difference in power between the two outputs.	$20\log_{10}\left(\frac{ S_{ki} }{ S_{mi} }\right)$
Phase Balance	The difference in phase angle between the two output ports.	$\angle S_{ki} - \angle S_{mi} + 90^\circ$
Group Delay	Group delay is defined as the average of the mean group delay of the coupling path and the mean group delay of the direct path.	Group delay (ns) = $\frac{Mean(GD(S_{mi})) + Mean(GD(S_{ki}))}{2}$ where "Mean" is the arithmetic mean of the group delay over a frequency band.

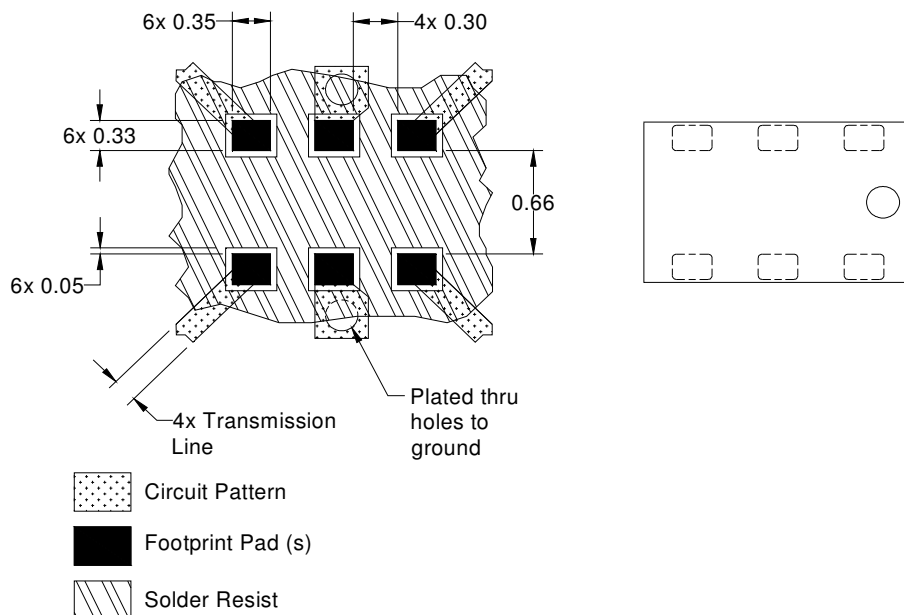
*100% RF test is performed per spec definition for pin configuration 1 and port 1 (input port) is connected to pin1, port 2 (isolated port) is connected to pin 3, port 3 (direct port) is connected to pin 4 and port 4 (isolated) is connected to pin 6.

Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

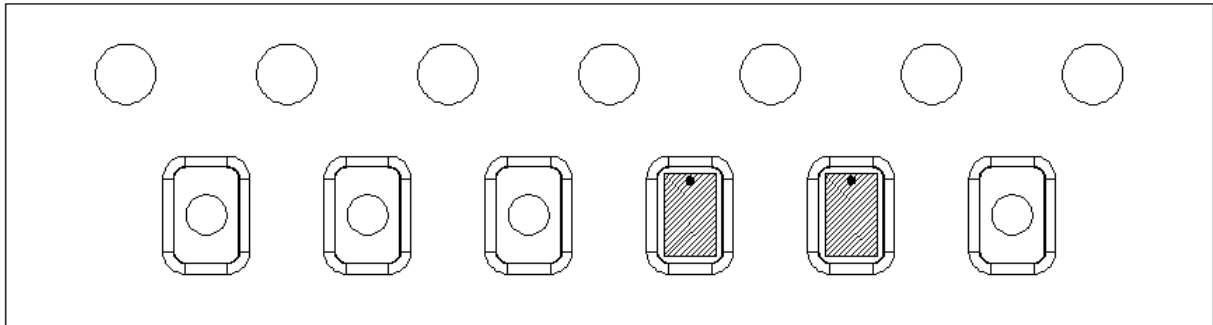
An example of the PCB footprint used in the testing of these parts is shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.

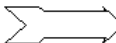


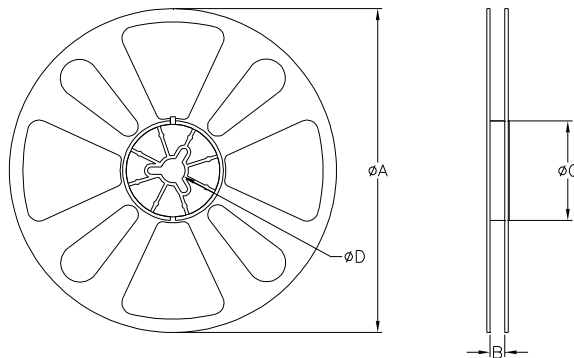
Dimensions are in Millimeters
Mounting Footprint

Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.



Direction of
Part Feed
(Unloading) 



QUANTITY/REEL	REEL DIMENSIONS mm	
4000	ϕA	177.80
	B	8.00
	ϕC	50.80
	ϕD	13.00